



SHRINK IT!

Microelectronics Solutions



- **Innovative, advanced microelectronics packaging solutions**
- **Customer focused program management and engineering support from design inception through product life cycle**
- **Validation and test**
- **Obsolescence management**

Solution Overview

Crane Microelectronics Solutions specializes in unique microelectronic packaging for customers requiring innovative approaches to resolving size, weight and circuit density challenges while maintaining high reliability. Microelectronics Solutions works with a variety of applications in the aerospace, military, medical, industrial and commercial markets including build-to-print, co-development or turnkey. We strive in meeting customers demand for time-to-market and time-to-volume.

Technical Capabilities

Our expertise is in high-density microelectronic module assembly with emphasis on reduced size, weight and increased reliability. Our product and test system development capabilities complement the expertise and experience gained in over 40 years of manufacturing chip-and-wire, chip-on-board, chip-on-flex, surface mount or mixed technology products.

Our facility is ITAR registered and certified to MIL-PRF-38534 Class H and K, ISO 13485, as well as to ISO 9001 and AS9100 assuring quality in all our services including design, development and production.

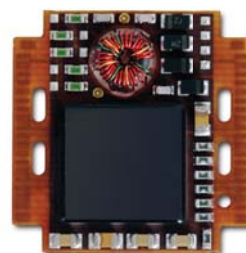
Crane Aerospace & Electronics team

Crane Aerospace & Electronics is a major supplier of systems and components for critical aerospace and defense applications. They are designed for some of the toughest environments – from engines to landing gear; satellites to medical implants; and missiles to unmanned aerial systems (UAS). From application engineering, through design and manufacturing, Crane Aerospace & Electronics offers a comprehensive approach to product specification, design certification and service.





- Hi-Rel mixed technology multi-chip-module (MCM)
- Double sided chip-on-board (COB) with glob top



- High-Rel MCM
- Chip-on-flex (CoF) with chip-scale-package (CSP)



- Traditional hermetic metal package hybrid
- Thick film MCM on alumina ceramic with thermally conductive copper block

Crane Aerospace & Electronics – Microelectronics Solutions www.cranae.com/microelec

ELDEC • Hydro-Aire • Interpoint • Keltec • Lear Romec • Merrimac • P.L. Porter • Signal Technology

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